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PRINTED CIRCUIT BOARD HAVING A MICROELECTRONIC
SEMICONDUCTOR DEVICE MOUNT AREA FOR TRACE ROUTING
THERETHROUGH

ABSTRACT OF THE DISCLOSURE

10 An optimal microelectronic semiconductor device mount area on a printed circuit board is provided. A novel mount area includes a plurality of collinear arrangements of attach pads and collinear arrangements of vias so that, at a minimum, at least one signal trace may be routed directly through the mount area. Additionally, capacitors may be coupled directly within the mount area on a bottom surface of the printed circuit board. The mount area includes a plurality of collinear arrangements of attach pads and a plurality of collinear arrangements of vias. Each of the collinear arrangements of attach pads are preferably separated from the nearest adjacent collinear arrangements of attach pads by an equivalent distance. A plurality of collinear arrangements of vias are separated from adjacent collinear arrangements of vias by a first distance. At least two mutually adjacent collinear arrangements of vias define a trace routing channel through the mount area.

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